## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Satoru MIYASHITA, Hiroshi KIGUCHI, Tatsuya SHIMODA and Sadao KANBE

Application No.: New Rule 1.53(b) Divisional of U.S.S.N. 09/101,083

Filed: July 10, 2001 Docket No.: 101050.02

For: METHOD OF MANUFACTURING ORGANIC EL ELEMENT, ORGANIC EL

ELEMENT, AND ORGANIC EL DISPLAY DEVICE

## PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office

Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

## IN THE CLAIMS:

Please cancel claims 1-24 without prejudice to or disclaimer of the subject matter contained therein

Please add new claims 25-75 as follows:

--25. A process for forming a pattern on a substrate by deposition of an organic material comprising the steps of:

depositing a semiconducting organic material in a solvent onto a substrate by ink-jet printing; and

evaporating the solvent, whereby said organic material remains on the substrate.--

- --26. The process of claim 25, further comprising drying the deposited material to remove said solvent.--
- --27. The process of claim 25 wherein said organic material is a luminescent polymer.--
- --28. The process of claim 25 wherein said material includes polyvinylcarbazol film.--
  - --29. The process of claim 25 wherein said solvent is chloroform.--
  - --30. The process of claim 25 wherein said material includes light emitting dyes.--
- --31. The process of claim 30 wherein said light emitting dyes include coumarin and nile red.--
  - --32. The process of claim 31 wherein said coumarin is coumarin 6.--
  - --33. The process of claim 31 wherein said coumarin is coumarin 47.--
- --34. The process of claim 31 wherein said coumarin is coumarin 6 and coumarin 47.--
- --35. The process of claim 25 wherein said organic material is a mixture of polymers and other organic molecules.--
- --36. A process for making organic light emitting diodes comprising the steps of: depositing a semiconducting organic material in a solvent onto a substrate by ink-jet printing; and
  - evaporating the solvent, said organic material remaining on the substrate.--
- --37. The process of claim 36 wherein said depositing step operates an ink-jet printer in a mode to create a continuous sheet of polymer.--
- --38. The process of claim 37 further including the step of metallizing said ink-jet printed substrates.--

- --39. The process of claim 38 further including the step of depositing with ink-jet printing top metal contacts on said substrate.--
- --40. The process of claim 39 wherein said top metal contacts are deposited through a shadow mask.--
- --41. The process of claim 36 further including the step of depositing with ink-jet printing bottom metal contacts on said substrate.--
- --42. The process of claim 39 wherein said top metal contacts are deposited in a pattern.--
- --43. The process of claim 41 wherein said bottom metal contacts are deposited in a pattern.--
- --44. The process of claim 36 further wherein said organic material includes light emitting dyes.--
- --45. The process of claim 44 further including the step of depositing top contacts on said organic material by ink jet printing.--
- --46. The process of claim 45 further including the step of depositing bottom contacts on said substrate by ink-jet printing.--
  - --47. A process of forming thin fillm field effect transistors comprising the steps of: forming a gate electrode on a substrate;

forming a gate insulator over said gate electrode;

forming a polymer semiconducting layer on said insulator by ink-jet printing;

and

forming source and drain contacts on said semiconducting layer .--

--48. The process of claim 47 wherein said gate insulator is formed by ink-jet printing, and the semiconducting layer by other techniques.--

- --49. The process of claim 47 wherein the source and drain contacts are applied directly on the gate insulator before the semiconducting layer is deposited.--
- --50. The process of claim 48 wherein the source and drain contacts are applied directly on the gate insulator before the semiconducting layer is deposited.--
- --51. The process of claim 47 wherein the semiconducting layer comprises a nonpolymeric organic film or a polymer/small organic molecule blend.--
- --52. The process of claim 48 wherein the semiconducting layer comprises a non-polymeric organic film or a polymer/small organic molecule blend,--
- --53. The process of claim 49 wherein the semiconducting layer comprises a non-polymeric organic film or a polymer/small organic molecule blend.--
- --54. A process for forming a pattern on a substrate by deposition of an organic material comprising the steps of:

depositing organic material including polyvinylcarbazol film in a solvent onto a substrate by ink-jet printing; and

evaporating the solvent, whereby said organic material remains on the substrate,--

- --55. The process of claim 54, further comprising drying the deposited material to remove said solvent.--
  - --56. The process of claim 54 wherein said organic material is semiconducting.--
- --57. The process of claim 54 wherein said organic material is a luminescent polymer.--
  - --58. The process of claim 54 wherein said solvent is chloroform.--
  - --59. The process of claim 54 wherein said material includes light emitting dyes.--
- --60. The process of claim 59 wherein said light emitting dyes include coumarin and nile red --

- --61. The process of claim 60 wherein said coumarin is coumarin 6.--
- --62. The process of claim 60 wherein said coumarin is coumarin 47.--
- --63. The process of claim 60 wherein said coumarin is coumarin 6 and coumarin 47.--
- --64. The process of claim 54 wherein said organic material is a mixture of polymers and other organic molecules.--
- --65. A process for making organic light emitting diodes comprising the steps of: depositing organic material including polyvinylcarbazol film in a solvent onto a substrate by ink-jet printing; and
  - evaporating the solvent, said organic material remaining on the substrate.--
- --66. The process of claim 65 wherein said depositing step operates an ink-jet printer in a mode to create a continuous sheet of polymer.--
- --67. The process of claim 66 further including the step of metallizing said ink-jet printed substrates.--
- --68. The process of claim 67 further including the step of depositing with ink-jet printing top metal contacts on said substrate.--
- --69. The process of claim 68 wherein said top metal contacts are deposited through a shadow mask.--
- --70. The process of claim 65 further including the step of depositing with ink-jet printing bottom metal contacts on said substrate.--
- --71. The process of claim 68 wherein said top metal contacts are deposited in a pattern.--
- --72. The process of claim 70 wherein said bottom metal contacts are deposited in a pattern.--

- --73. The process of claim 65 further wherein said organic material includes light emitting dyes.--
- --74. The process of claim 73 further including the step of depositing top contacts on said organic material by ink jet printing.--
- --75. The process of claim 74 further including the step of depositing bottom contacts on said substrate by ink-jet printing.--

## REMARKS

Claims 25-75 are pending. By this Amendment, claims 1-24 are canceled, and claims 25-75 are added.

Prompt and favorable examination on the merits is respectfully requested.

Respectfully submitted,

James A. Oliff Registration No. 27,075

Eric D. Morehouse Registration No. 38,565

JAO:EDM/gam

Date: July 10, 2001

OLIFF & BERRIDGE, PLC P.O. Box 19928 Alexandria, Virginia 22320 Telephone: (703) 836-6400 DEPOSIT ACCOUNT USE AUTHORIZATION

Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461